

## RoHS Compliance Definition

The definition of a RoHS compliant component involves six materials listed below and not just lead:

Material	Allowable Amount
Lead (Pb)	0.1% by weight at raw homogeneous materials level
Cadmium (Cd)	< 0.01% by weight at raw homogeneous materials level
Mercury (Hg)	100 ppm or less; Not intentionally added
Hexavalent chromium (Hex-Cr)	< 0.01% by weight at raw homogeneous materials level
Polybrominated biphenyls (PBB – fire retardant)	0.1% by weight at raw homogeneous materials
Polybrominated diphenyl ethers (PBDE – fire retardant)	0.1% by weight at raw homogeneous materials

## Process Temperatures

All components will be expected to withstand the temperatures listed in the Jedec 020 specification. The current revision (B) is under revision and is being updated to reflect the higher temperatures required for lead free assembly. It is expected that the 020 specification evolves that all components will be able to withstand the latest revision of the document.

The table below is the currently proposed but not yet approved changes to the 020 specification:

### **PROPOSED**

**Table 4-1 - Package Peak Reflow Temperatures**

<b>SnPb Eutectic Process</b>		
<b>Package Thickness</b>	<b>Volume mm<sup>3</sup> &lt;350</b>	<b>Volume mm<sup>3</sup> ≥ 350</b>
<b>&lt;2.5 mm</b>	240 +0/-5 °C	225 +0/-5°C
<b>≥ 2.5 mm</b>	225 +0/-5°C	225 +0/-5°C

<b>Pb-free Process</b>			
<b>Package Thickness</b>	<b>Volume mm<sup>3</sup> &lt; 350</b>	<b>Volume mm<sup>3</sup> 350 - 2000</b>	<b>Volume mm<sup>3</sup> &gt; 2000</b>
<b>&lt; 1.6 mm</b>	260 +0/-5 °C	260 +0/-5 °C	260 +0/-5 °C
<b>1.6 mm - 2.5 mm</b>	260 +0/-5 °C	250 +0/-5 °C	250 +0/-5 °C
<b>&gt; 2.5 mm</b>	250 +0/-5 °C	250 +0/-5 °C	245 +0/-5 °C